PTFE/Woven Fiberglass/Ceramic Filled Laminate for Microwave Printed Circuit Boards

Features:
- Ceramic Filled
- Dielectric Constant (4.5)
- High Thermal Conductivity
- Large Panel Size

Benefits:
- Superior PTH Adhesion
- Readily Replaces FR-4
- Heat Dissipation and Mgmt
- Multiple Boards/Panel; Larger Circuit Formats

Typical Applications:
- Circuit Board Miniaturization
- Replacement of FR-4 in Higher Frequency Applications
- Wideband Antenna Applications

Arlon’s AD450 is a woven fiberglass reinforced, ceramic filled, PTFE based composite material for use as a printed circuit board substrate. It can be specified to replace Arlon AR450, a composite with similar electrical properties, but based on non-woven fiberglass reinforcement. The shift to woven fiberglass provides better dielectric constant and thickness uniformity, better dimensional stability as well as reduced manufacturing costs.

The electrical properties of AD450 suggest it can readily replace FR-4 in applications where higher frequencies and expectations for increased fidelity with broadband signal are beyond the performance offered by FR-4. With a dielectric constant of 4.5, most FR-4 designs can be readily transferred. Its higher thermal conductivity and lower CTE also promote its use in higher power designs, where temperature extremes and heat rejection are primary considerations.

AD450 is compatible with processing used for standard PTFE based printed circuit board substrates. In addition, its low Z-axis thermal expansion will improve plated through hole reliability, compared to typical PTFE based laminates.
## Typical Properties: AD450

<table>
<thead>
<tr>
<th>Property</th>
<th>Test Method</th>
<th>Condition</th>
<th>Result</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dielectric Constant @ 200 MHz</td>
<td>IPC TM-650 2.5.5.6</td>
<td>C23/50</td>
<td>4.50</td>
</tr>
<tr>
<td>Loss Tangent @ 200 MHz</td>
<td>IPC TM-650 2.5.5.6</td>
<td>C23/50</td>
<td>0.0035</td>
</tr>
<tr>
<td>Thermal Coefficient of Er</td>
<td>IPC TM-650 2.5.5.5</td>
<td>-10°C to +140°C</td>
<td>-233.5</td>
</tr>
<tr>
<td>Copper Peel Strength (lb/in)</td>
<td>IPC TM-650 2.4.8</td>
<td>A, TS</td>
<td>&gt;12</td>
</tr>
<tr>
<td>Volume Resistivity (MΩ-cm)</td>
<td>IPC TM-650 2.5.17.1</td>
<td>C96/35/90</td>
<td>1.2 x 10⁹</td>
</tr>
<tr>
<td>Surface Resistivity (MΩ)</td>
<td>IPC TM-650 2.5.17.1</td>
<td>C96/35/90</td>
<td>4.5 x 10⁷</td>
</tr>
<tr>
<td>Arc Resistance (seconds)</td>
<td>ASTM D-495</td>
<td>D48/50</td>
<td>&gt;180</td>
</tr>
<tr>
<td>Tensile Modulus (kpsi)</td>
<td>ASTM D-638</td>
<td>A, 23°C</td>
<td>&gt;700</td>
</tr>
<tr>
<td>Tensile Strength (kpsi)</td>
<td>ASTM D-882</td>
<td>A, 23°C</td>
<td>&gt;20</td>
</tr>
<tr>
<td>Compressive Modulus (kpsi)</td>
<td>ASTM D-695</td>
<td>A, 23°C</td>
<td>&gt;350</td>
</tr>
<tr>
<td>Flexural Modulus (kpsi)</td>
<td>ASTM D-790</td>
<td>A, 23°C</td>
<td>&gt;540</td>
</tr>
<tr>
<td>Dielectric Breakdown (kV)</td>
<td>ASTM D-149</td>
<td>D48/50</td>
<td>&gt;45</td>
</tr>
<tr>
<td>Density (g/cm³)</td>
<td>ASTM D-792 Method A</td>
<td>A, 23°C</td>
<td>2.45</td>
</tr>
<tr>
<td>Water Absorption (%)</td>
<td>IPC TM-650 2.6.2.2</td>
<td>E1/105 + D24/23</td>
<td>0.07</td>
</tr>
<tr>
<td>Coefficient of Thermal Expansion (ppm/°C)</td>
<td>IPC TM-650 2.4.24</td>
<td>TMA</td>
<td></td>
</tr>
<tr>
<td>X Axis</td>
<td></td>
<td></td>
<td>8</td>
</tr>
<tr>
<td>Y Axis</td>
<td></td>
<td></td>
<td>11</td>
</tr>
<tr>
<td>Z Axis</td>
<td></td>
<td></td>
<td>42</td>
</tr>
<tr>
<td>Thermal Conductivity (W/mK)</td>
<td>ASTM E-1225</td>
<td>100°C</td>
<td>0.38</td>
</tr>
<tr>
<td>Outgassing</td>
<td>NASA SP-R-0022A</td>
<td>Maximum 1.00%</td>
<td>0.01</td>
</tr>
<tr>
<td>Total Mass Loss (%)</td>
<td></td>
<td>Maximum 0.10%</td>
<td>0.01</td>
</tr>
<tr>
<td>Collected Volatile Condensable Material (%)</td>
<td></td>
<td>125°C, ≤10⁻⁶ torr</td>
<td>0.00</td>
</tr>
<tr>
<td>Water Vapor Recovered</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Flammability</td>
<td>UL 94 Vertical Burn</td>
<td>C48/23/50, E24/125</td>
<td>UL94-V0</td>
</tr>
</tbody>
</table>

**Material Availability:**
AD450 laminate is available in 0.020", 0.030", and 0.060" thicknesses (other thicknesses may be available by contacting Arlon’s customer service). AD450 is supplied with 1/2, 1 or 2 ounce electrodeposited (ED) copper on both sides. Other copper weights and rolled copper foil are available. AD450 is also available bonded to heavy metal ground planes. Aluminum, brass or copper plate can provide an integral heat sink and mechanical support to the substrate.

When ordering AD450 product, please specify thickness, copper cladding, panel size, and any other special considerations.

*Results listed above are typical properties; they are not to be used as specification limits. The above information creates no expressed or implied warranties. The properties of Arlon laminates may vary, depending on the design and application.*
AD450 Laminate

Figure 1

Demonstrates the Stability of Dielectric Constant across Frequency. This information was correlated from data generated by using a free space and circular resonator cavity. This characteristic demonstrates the inherent robustness of Arlon Laminates across Frequency, thus simplifying the final design process when working across EM spectrum. When transitioning from FR-4 designs to higher frequency, the stability of the Dielectric Constant of AD450 over frequency ensures easy design transition and scalability of design.

Figure 2

Demonstrates the Stability of Dissipation Factor across Frequency. This characteristic demonstrates the inherent robustness of Arlon Laminates across Frequency, providing a stable platform for high frequency applications where signal integrity is critical to the overall performance of the application.

Results listed above are typical properties; they are not to be used as specification limits. The above information creates no expressed or implied warranties. The properties of Arlon laminates may vary depending on the design and application.
For samples, technical assistance, customer service or for more information, please contact Arlon Materials for Electronics Division at the following locations:

**NORTH AMERICA:**
Arlon, Inc.
Electronic Substrates
9433 Hyssop Drive
Rancho Cucamonga, CA 91730
Tel: (909) 987-9533
Fax: (909) 987-8541

Arlon, Inc.
Microwave Materials
1100 Governor Lea Road
Bear, DE 19701
Tel: (800) 635-9333
Outside U.S. & Canada: (302) 834-2100
Fax: (302) 834-2574

**SOUTHERN CHINA:**
Arlon, Inc.
Room 805, Unit 3, Bldg 4
Liyuan, Xincun Holiday Road
Huaqiao Cheng, Shenzhen 518053
China
Tel/Fax: (86) 755-269-066-12

**NORTHERN CHINA:**
Arlon, Inc.
Room 11/401, No. 8
Hong Gu Road
Shanghai, China 200336
Tel/Fax: (86) 21-6209-0202

**EUROPE:**
Arlon, Inc.
44 Wilby Avenue
Little Lever
Bolton, Lancashire BL31QE
United Kingdom
Tel: (44) 120-457-6068
Fax: (44) 120-479-6463

Or visit us on the web at:
www.arlon-med.com